SDLS131 - APRIL 1985 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

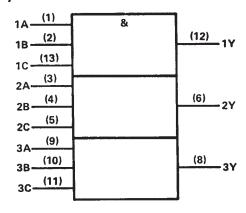
These devices contain three independent 3-input AND gates.

The SN54LS11 and SN54S11 are characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to 125 °C. The SN74LS11 and SN74S11 are characterized for operation from 0 °C to 70 °C.

#### **FUNCTION TABLE (each gate)**

II	VPUT	s	OUTPUT
Α	В	С	Y
Н	Н	н	Н
L	X	X	L
×	L	x	L
х	X	L	L

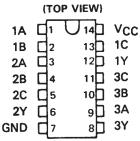
## logic symbol†



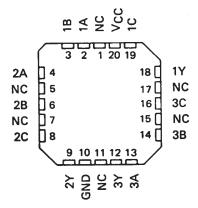
<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS11, SN74S11 . . . J OR W PACKAGE SN74LS11, SN74S11 . . . D OR N PACKAGE

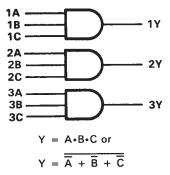


SN54LS11, SN54S11 . . . FK PACKAGE (TOP VIEW)

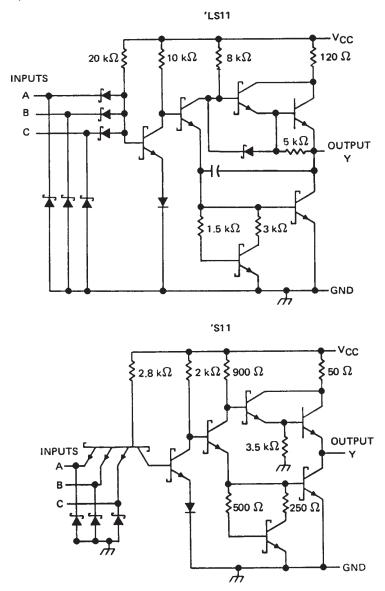


NC-No internal connection

### logic diagram (positive logic)



#### schematics (each gate)



Resistor values shown are nominal.

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	7 V
Input voltage: 'S11	5.5 V
'LS11	7 V
Operating free-air temperature range	SN54'
	SN74' 0°C to 70°C
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



#### recommended operating conditions

			SN54LS1	11	S	N74LS1	1	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	٧
ЮН	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		7507 00401		SN54LS	11	S	N74LS1	1	LINIT	
PARAMETER		TEST CONDI	TIONS T	MIN	TYP‡	MAX	MIN	TYP ‡	MAX	UNIT
VIK	V <sub>CC</sub> = MIN,	I <sub>I</sub> = - 18 mA				<b>– 1.5</b>			- 1.5	٧
Vон	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OH</sub> = - 0.4 mA	2.5	3.4		2.7	3.4		V
V	V <sub>CC</sub> = MIN,	VIL = MAX,	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V <sub>CC</sub> = MIN,	VIL = MAX,	I <sub>OL</sub> = 8 mA					0.35	0.5	V
11	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V				0.1			0.1	mA
Чн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	μΑ
IIL.	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				- 0.4			- 0.4	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V			1.8	3.6		1.8	3.6	mA
ICCL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0 V			3.3	6.6		3.3	6.6	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	A, B or C	<b>&gt;</b>	$R_1 = 2 k\Omega$ ,	C <sub>1</sub> = 15 pF		8	15	ns
tPHL	A, B 01 0	<b>'</b>	11 - 2 K32,	CL - 15 pr		10	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

#### recommended operating conditions

			SN54S11			SN74S11		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			0.8			0.8	٧
ЮН	High-level output current			- 1			<b>– 1</b>	mA
lor	Low-level output current			20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		7507 0011017	10110 +		SN54S1	1		SN74S11	1	UNIT
PARAMETER		TEST CONDIT	IONS T	MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	CIVIT
VIK	V <sub>CC</sub> = MIN,	I <sub>1</sub> = - 18 mA				- 1.2			- 1.2	٧
V <sub>OH</sub>	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OH</sub> = - 1 mA	2.5	3.4		2.7	3.4		٧
VOL	V <sub>CC</sub> = MIN,	V <sub>1L</sub> = 0.8 V,	1 <sub>OL</sub> = 20 mA			0.5			0.5	٧
I <sub>I</sub>	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V				1			1	mA
lн	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V				50			50	μА
l <sub>IL</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.5 V				- 2			- 2	mA
IOS §	V <sub>CC</sub> = MAX			-40		- 100	- 40		- 100	mA
Іссн	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 4.5 V			13.5	24		13.5	24	mA
ICCL	V <sub>CC</sub> = MAX,	V1 = 0 V			24	42		24	42	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	ТҮР	MAX	UNIT
<sup>t</sup> PLH			P. = 290 O	C. = 15 oF		4.5	7	ns
<sup>t</sup> PHL	A, B or C	Y	R <sub>L</sub> = 280 Ω,	C <sub>L</sub> = 15 pF		5	7.5	ns
<sup>t</sup> PLH	A, B 01 C	*	D 200 O	2 - 52 - 5	6	6		ns
tpHL			R <sub>L</sub> = 280 Ω,	C <sub>L</sub> = 50 pF		7.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





24-Aug-2018

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/08001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 08001BCA	Samples
JM38510/08001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 08001BDA	Samples
JM38510/31001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31001BCA	Samples
JM38510/31001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31001BDA	Samples
M38510/08001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 08001BCA	Samples
M38510/08001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 08001BDA	Samples
M38510/31001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31001BCA	Samples
M38510/31001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31001BDA	Samples
SN54LS11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS11J	Samples
SN54S11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S11J	Samples
SN74LS11D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS11	Samples
SN74LS11DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS11	Samples
SN74LS11DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS11	Samples
SN74LS11N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS11N	Samples
SN74LS11NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS11N	Samples
SN74LS11NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS11	Samples
SNJ54LS11FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 11FK	Samples



## PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54LS11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS11J	Samples
SNJ54LS11W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS11W	Samples
SNJ54S11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S11J	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

24-Aug-2018

#### OTHER QUALIFIED VERSIONS OF SN54LS11, SN74LS11:

• Military: SN54LS11

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 8-Apr-2013

## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS11DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

www.ti.com 8-Apr-2013



#### \*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74LS11DR	SOIC	D	14	2500	367.0	367.0	38.0

# FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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